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PATENT NUMBER and  
ISSUE DATE

## U.S. UTILITY Patent Application

APPL NUM 10070000	FILING DATE 11/27/2002	CLASS 205	SUBCLASS 24	GAU 1741	EXAMINER Wong
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\*\*APPLICANTS: Hu Jung-Chih; Gau Wu-Chun; Chang Ting-Chang; Feng Ming-Shiann; Cheng Chun-Lin; Lin You-Shin; Li Ying-Hao; Chen Lih-Juann;

## \*\*CONTINUING DATA VERIFIED:

This application is a 371 of PCT/EP00/08312 08/25/2000

\*\* FOREIGN APPLICATIONS VERIFIED:  
GERMANY 199 41 605.2 09/01/1999

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PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed 35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no
Verified and Acknowledged Examiners's initials		ATTORNEY DOCKET NO MERCK 2395
TITLE : Galvanizing solution for the galvanic deposition of copper		
U.S. DEPT. OF COMM/PAT. & TM-PTO-435L(Rev. 12-94)		

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner	
ISSUE FEE		Primary Examiner	
Amount Due	Date Paid	Total Claims	Print Claim for O.G.
		DRAWING	
		Sheets Drwg.	Figs. Drwg.
		Print Fig.	
TERMINAL		PREPARED FOR ISSUE	
DISCLAIMER		Application Examiner	
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